LIGHT EMITTING DIODE SPECIFICATION

CUSTOMER NAME:

DESCRIPTION: E6T3535IRPC1UDA

REVISION： V2.2

ISSUE DATE： 2018-07-25

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Features:

- ●Excellent heat conductive assembly.
- ●High radiant intensity.
- ●Wide viewing angle.
- ●Soldering methods: IR reflow soldering
- ●The product itself will remain within RoHS

Application:

- ●Surveillance
- ●Face Recognition
- ●Date Communication

Part Number	Dice Material	Emitted Color	Lens Color
E6T3535IRPC1UDA	GaAlAs	Infrared	Water Clear

Electro-Optical Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Radiant Intensity	IE	If=1A	1500.0	-	2000.0	mW
Radiation Bandwidth	△λ	If=1A	-	30	-	nm
Forward Voltage	Vf1	If=10uA	1.40	-	-	V
	Vf2	If=1A	-	2.90	3.30	
Peak Wavelength	λP	If=1A	840	855	870	nm
Viewing Angle	2θ1/2	If=1A	-	120	-	deg
Reverse Current	IR	Vr≤10V	-	-	5.0	uA

Absolute Maximum Ratings(Ta=25℃)

Parameter	Symbol	Max.	Unit
Peak Forward Current(1/10 Duty Cycle, 0.1ms Pulse Width)	IFP	1500	mA
Forward Current	IF	≤1000	mA
Reverse Voltage	VR	5	v
Junction Temperature	T_j	≤115	°C
Electrostatic Discharge	ESD	2000	v
Operating Temperature Range	Topr	-40to+85	°C
Storage Temperature Range	Tstg	-40to+85	°C
Reflow Soldering	Tsld	280℃for 10secs	

Optical & Electrical Characteristics

Fig.1 – Relative Radiant Flux vs. Forward Current

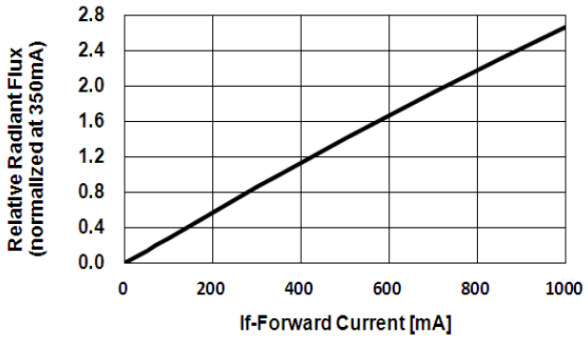


Fig.2 – Forward Current vs. Forward Voltage

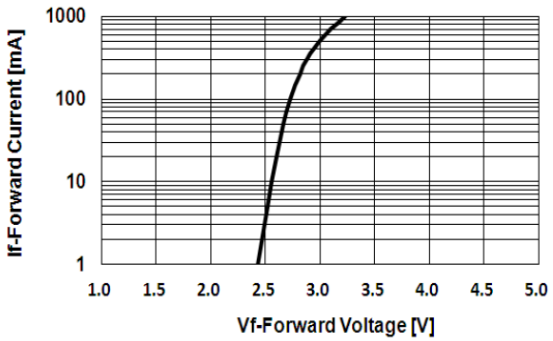


Fig.3 – Relative Radiant Flux (@350mA) vs. Ambient Temperature

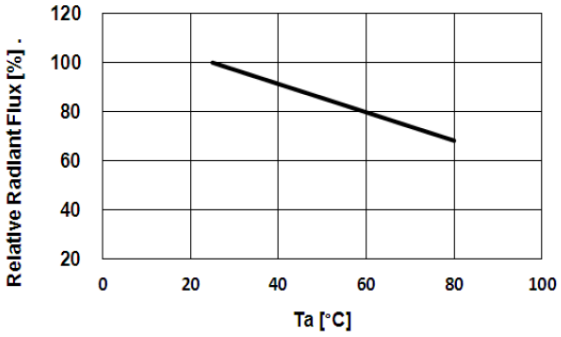


Fig.4 – Forward Voltage (@350mA) vs. Ambient Temperature

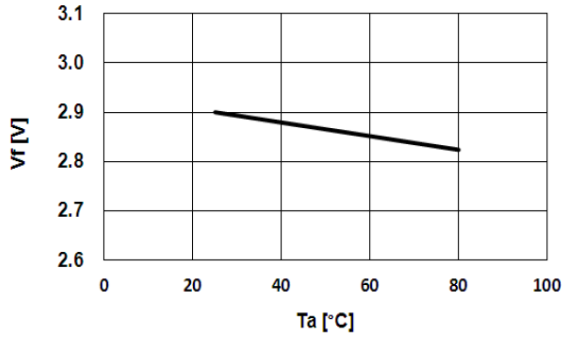


Fig.5 – Peak Wavelength (@350mA) vs. Ambient Temperature

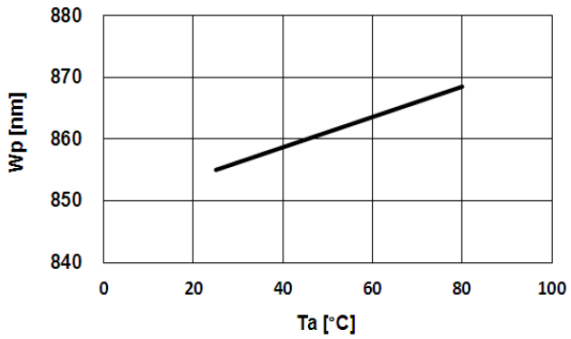
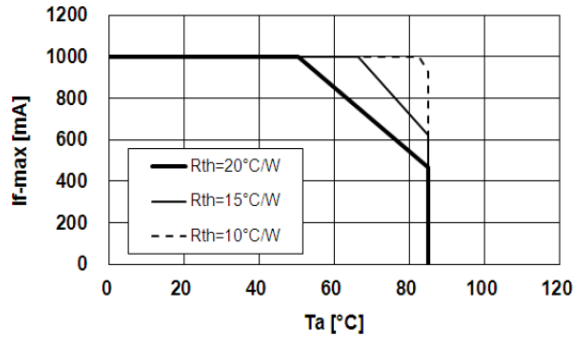


Fig.6 – Maximum Driving Forward DC Current vs. Ambient Temperature (De-rating based on Tj max. = 115°C)



Bin Limits

Bin Range Of Radiant Intensity (Unit:mw/sr)

Bin Code	Min	Max	Condition
L1	1500	1750	If=1A
L2	1750	2000	
L3	-	-	
L4	-	-	

Bin Range Of Forward Voltage (Unit:V)

Bin Code	Min	Max	Condition
V1	2.9	3.1	If=1A
V2	3.1	3.3	
V3	-	-	
V4	-	-	
V5	-	-	

Notes:

1.Tolerance of Luminous Intensity ±10%

2.Tolerance of Forward Voltage ±0.1V

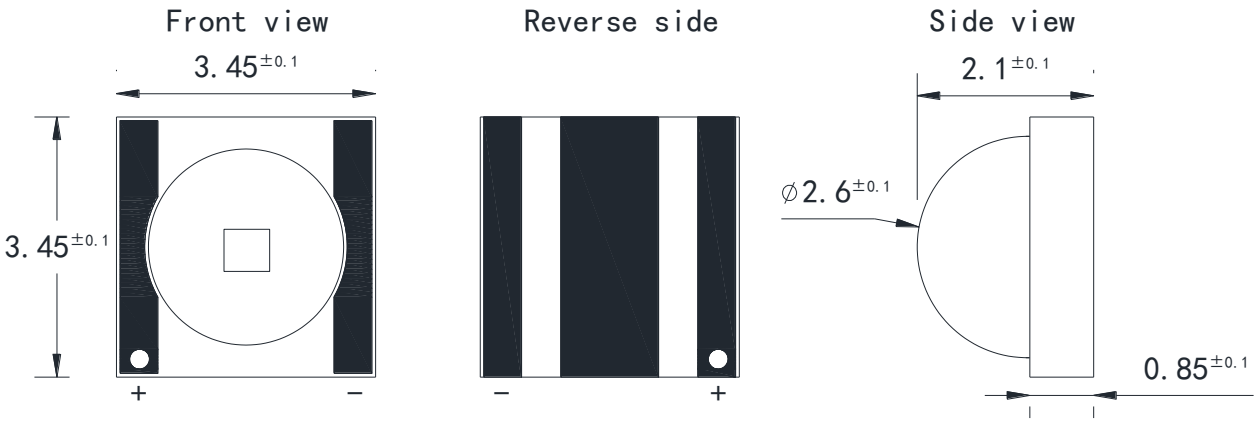
Reliability Test Items And Conditions

Test Items	Reference	Test Conditions	Time	Quantity	Criterion
Thermal Shock	MIL-STD-202G	-40℃ (30min) -100℃ (30min)	100 Cycles	22	0/22
Temperature And Humidity Cyclic	JEITA ED-4701 200 203	-10℃~65℃; 0%~90%RH	10cycles	22	0/22
High Temperature Storage	JEITA ED -4071 200 201	Ta=100℃	1000H	22	0/22
Low Temperature Storage	JEITA ED -4071 200 202	Ta=-40℃	1000H	22	0/22
High Temperature High Humidity Storage	JEITA ED -4071 100 103	Ta=60℃; RH=90%	1000H	22	0/22
High Temperature Life Test	JESD22-A108D	Ta=80℃	1000H	22	0/22
Life Test	JESD22-A108D	Ta=25℃ IF=1A	1000H	22	0/22
Resistance to Sodering Heat	GB/T 4937, Ⅱ, 2.2&2.3	Tsol*=(240±5)℃10secs	2 times	22	0/22

Criteria For Judging Damage

Test Items	Symbol	Test Conditions	Criteria For Judging Damage
Forward Voltage	V_F	$I_F=I_{FT}$	Initial Data±10%
Recerse Current	I_R	V_R=5V	I_R≤10uA
Luminous Intensity	IV	$I_F=I_{FT}$	Average I_V degradation≤30% ; Single LED I_V degradation≤50%
Resistance to Soldering Heat	-	-	Meterial without internal cracks,no meterial between stripped,no deaded light

Product size (Unit:mm)

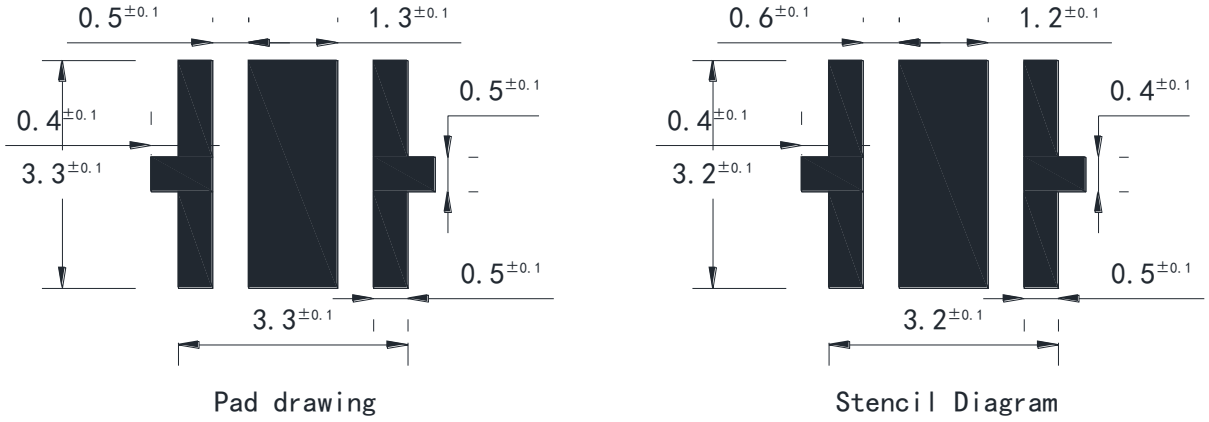


NOTES：

1. All dimensions are in millimeters (inches)

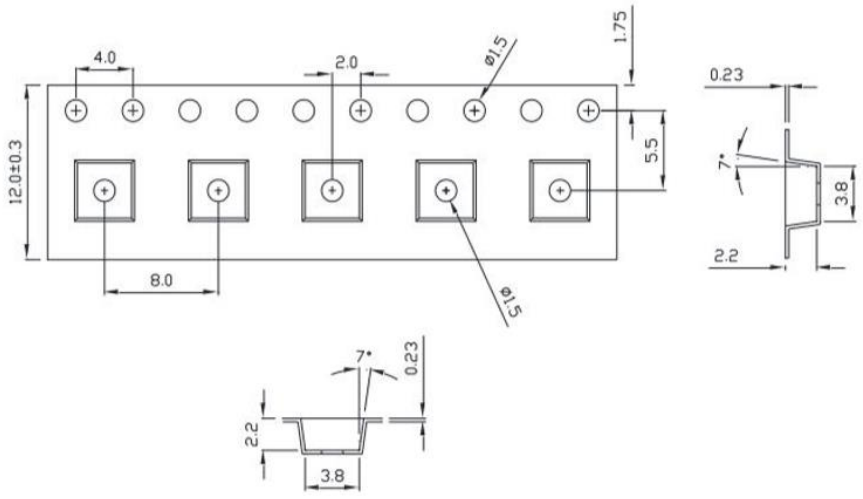
2. Tolerances are ±0.2mm (0.008inch) unless otherwise noted

Recommended Soldering Pad Design (Unit:mm)

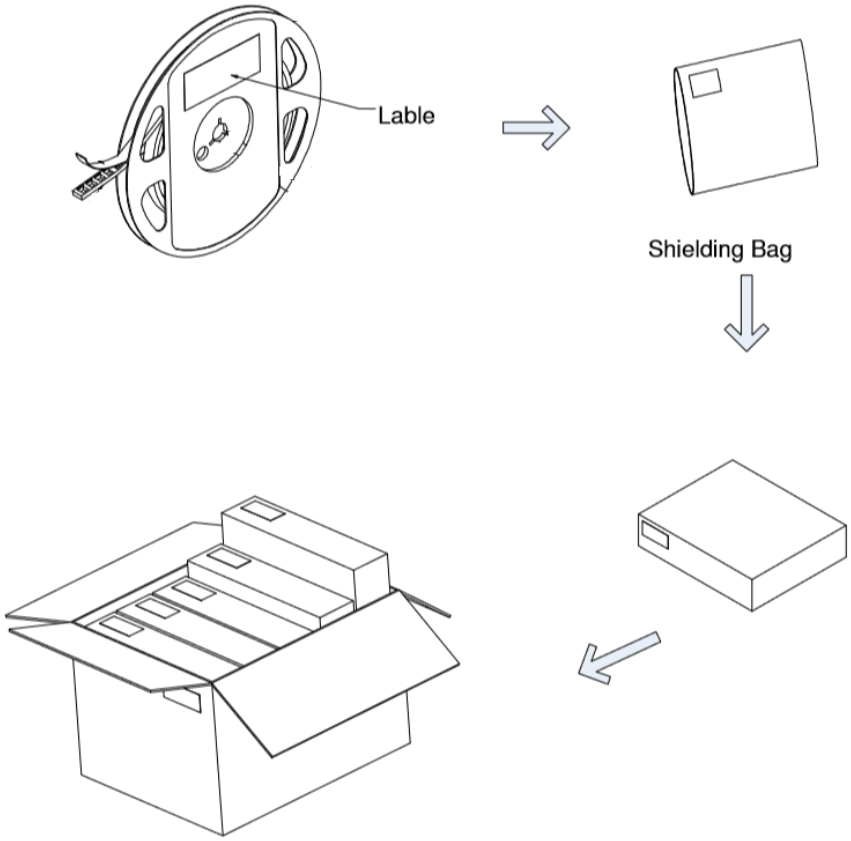


Taping and package Spec

●Tape Specification:1,000pcs Per Reel



Packaging



LabelStyle

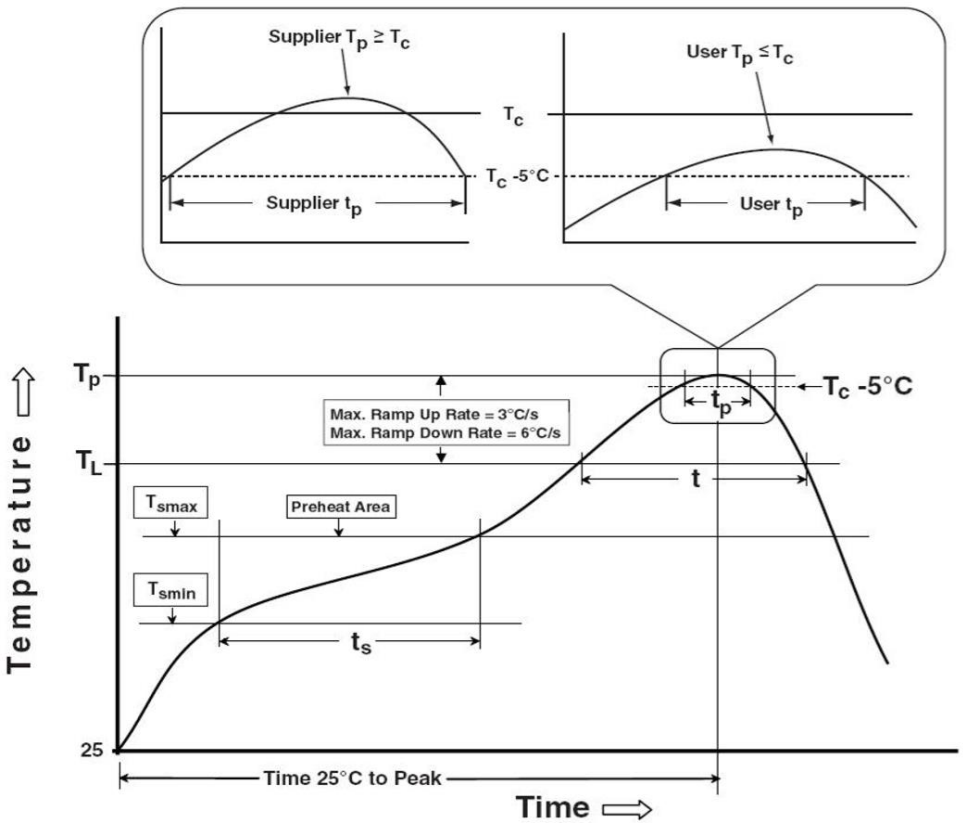
EKINGLUX OPTOELECTRONICS(SHANGHAI) CO.,LTD
TEL:86 21 59909181 Sales@ekingluxs.com
P/N:XXXXXXXXXXXXXXX
Emitting Color: XXXX
HUE: XXX-XXX nm
IV : XXX-XXX mcd example
VF: XX-XX V BIN Code: XX
QTY: XX PCS DATE: XXXX/XX/XX
LOT NO.:XXXXXXX

Table of Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	100 °C 150°C 60-120 seconds	150 °C 200 °C 60-120 seconds
Average ramp-up rate (Tsmax to Tp)	3 °C/second max	3 °C/second max
Liquidous temperature (TL) Time at liquidous (tL)	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak package body temperature (Tp)*	230 °C ~235 °C	255 °C ~260 °C
Classification temperature (Tc)	235 °C	260 °C
Time (tp) within 5 °C of the specified Classification temperature (Tc)	20 seconds	30 seconds
Average ramp-down rate (Tp to Tsmax)	6 °C/second max	6 °C/second max
Time 25 °C to peak temperature	6 minutes max	8 minutes max

1. Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

2.Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.



Precautions

1. Storage：

●Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to aminimum.

●Before opening the package, the product should be kept at 30℃ or less and humidity less than 60% RH, and beused within a year.

●After opening the package, the product should be stored at 30℃ or less and humidity less than 10%RH. It is recommended that the product be operated at the workshop condition of 30℃ or less and humidity less than 60%RH.

●If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (70±5)℃ for 24 hours.

2. Static Electricity：

Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristic such as the forward voltage becomes lower, or the LEDs do not light at the low current. even not light.

All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

3. Vulcanization：

LED curing is due to sulfur being in bracket and the +1 price of silver in the chemical reaction generated Ag2S in the process. It will lead to the capacity of reflecting of silver layer reducing, light color temperature drift and serious decline ,seriously affecting the performance of the product.So we should take corresponding measures to avioding vulcanization, such as to avoid using sulphur volatile substances and keeping away from high sulphur content of the material.